

LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-18-1000	REV	2
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* 1000 Series Connector System *

This product specification contains the test method, the following datum are the general performance and requirements of the LEOCO 1000 series connector

1. Construction and dimensions shall be in accordance with the referenced drawings.

产品结构及尺寸依据所提供的图面。

2. Characteristics 特性:

Current rating 额定电流: 1 A AC,DC

Voltage rating 额定电压: 50V AC,DC

Temperature rating 额定温度: -25°C ~ +85°C

Applicable wire 适用的线: conductor construction size #28 ~ #30

3. Electrical performance 电气性能:

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需求
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method EIA-364-23	Initial: 20 mΩ max.
3-2	Insulation Resistance 绝缘阻抗	It should be tested in accordance with Method EIA-364-21.	Initial: 100 MΩ min.
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connectors shall be tested in accordance with method EIA-364-20 when the AC 500 V rms for one minute applied between adjacent contacts.	No evidence of break-down and flashover

4. Mechanical Performance 机械特性:

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需求
4-1	Crimp Tensile Strength 铆合张力强度	Pulling load shall be applied between correctly crimped contact and wire at a constant speed. Pulling speed: 25 mm / minute.	AWG #28: 1.0kgf min. AWG #30: 0.8kgf min.
4-2	Contact Insertion Force 接触插入力	The force required to insert a contact into a housing. Inserting speed: 25 mm / minute.	0.5kgf max.
4-3	Contact removal Force 接触拨出力	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm / minute.	0.5Kgf min.
4-4	Pin retention Force pin 保持力	Apply axial push force at the speed rate of 25mm/minute.	0.3 kgf min.
4-5	Insertion & Withdrawal Force 插拔力	Insert and withdraw connectors at the speed rate of 25±3mm/minute.	Refer to paragraph 6
4-6	Durability 耐久性	It should be tested in accordance with method EIA-364-09. Insert and withdraw connectors 30 cycles repeatedly by rate of less than 10 cycles per minute.	No defects. Contact resistance: 40 mΩ max.

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需求
4-7	Vibration 振动性	The connector mated PCB shall be vibrated in accordance with method EIA-364-28 tested condition B. Frequency:10-55-10 Hz/min. Amplitude: 1.52mm Period:2 hours for each direction.	Appearance: No damage Contact resistance: 40 mΩ max. Discontinuity : 1.0 micro second MAX.

5. Environmental Performance 环境特性:

ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需求
5-1	Humidity 耐湿性	The unmated connector shall be tested in accordance with method EIA-364-31 test procedure type I condition B. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.	NO damage. Contact resistance less than twice of initial. Insulation resistance: to paragraph 3-2. Dielectric withstand ing voltage: to paragraph 3-3
5-2	Salt Spray 盐雾试验	Connector shall be tested in accordance with method EIA-364-26 Temperature: 35±2 °C Density: 5 % in weight. Period: 24 hours.	NO damage. Contact resistance less than twice of initial.
5-3	Solderability 着锡性	Connector termination ends shall be checked for solderadility in accordance with method EIA-364-52. Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.	NO damage. Minimum: 95 % of immersed area.
5-4	Resistance to Soldering Heat 耐高温焊接	Specimen shall be mounted on PCB. Solder temperature: 250±5 °C Immersion period: 5±0.5 sec.	NO damage and deformation.

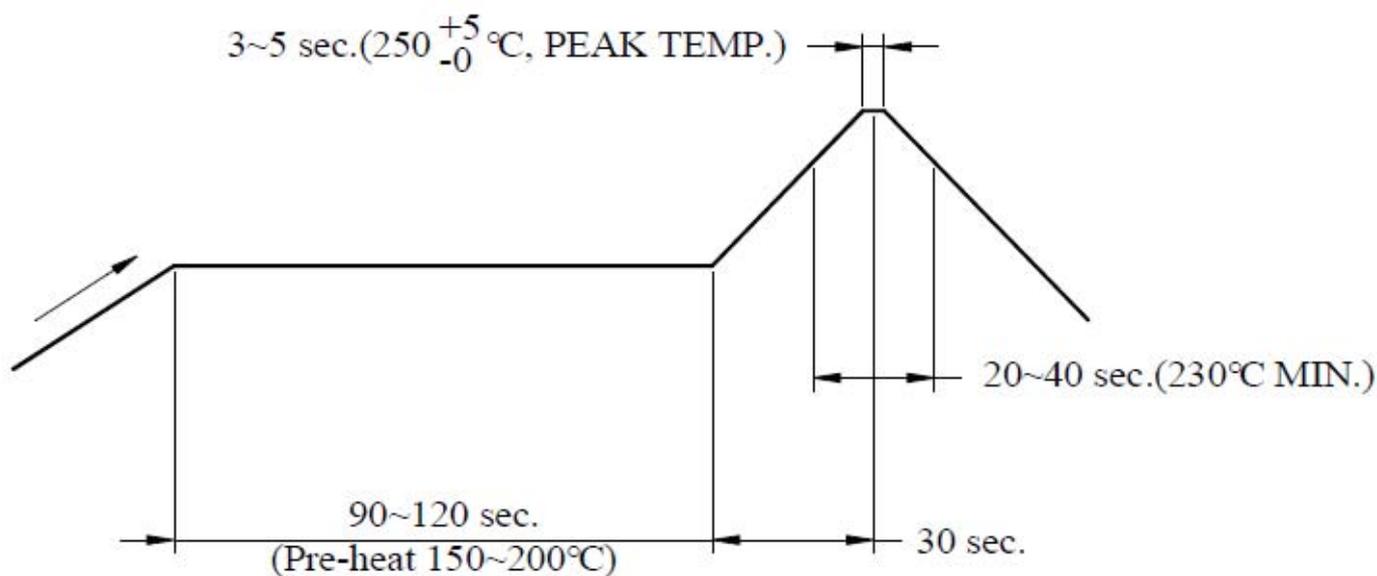
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需求
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6. 1000 Series Mating force and unmating force:

Unit: Kgf

Number of Circuits	Mating Force(max.)	Unmating Force(min.)
single	0.20kg	0.03kg
8	1.60kg	0.20kg
14	2.80kg	0.35kg
20	4.00kg	0.50kg
30	6.00kg	0.75kg

7. INFRARED REFLOW CONDITION



TEMPERATURE CONDITION GRAPH
(TEMPERATURE ON BOARD PATTERN SIDE)

NOTE: Please check the mount condition(reflow soldering condition) by your own devices beforehand, because the condition changes by the soldering devices, p.c.boards, and so on. No moisture treatment before reflow process.

核准: Chard	审核: Dylan	制作: Angel 2018-12-7
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